

**SEMICONDUCTOR PACKAGE AND LEADFRAME WITH HORIZONTAL
LEADS SPACED IN THE VERTICAL DIRECTION AND METHOD OF MAKING**

Donald Craig Foster

ABSTRACT OF THE DISCLOSURE

[0069] A leadframe, a semiconductor package, and methods of making the same are disclosed. A leadframe includes leads having an inner end segment. A first subset of the leads include a recess in a first surface of the inner end segment. A second subset of the leads include a recess in an opposite second surface of the inner end segment. The first subset leads are in an alternating lateral pattern with the second subset leads such that the recess of adjacent inner end segments are oriented in opposite directions. The recesses separate adjacent inner end segments in a vertical direction, thereby eliminating or reducing a need for horizontal spacing between adjacent inner end segments. In a semiconductor package, a semiconductor chip is electrically connected by a bond wire to the inner end segment of the leads. The bond wire is bonded within the recess of alternating leads.